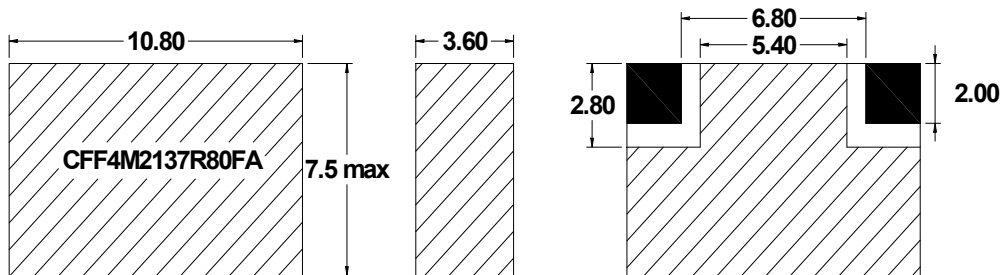




Electrical Specification

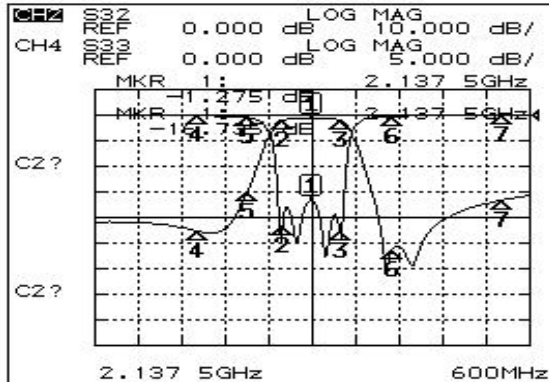
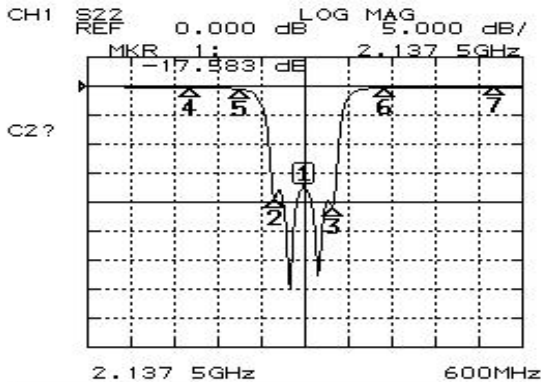
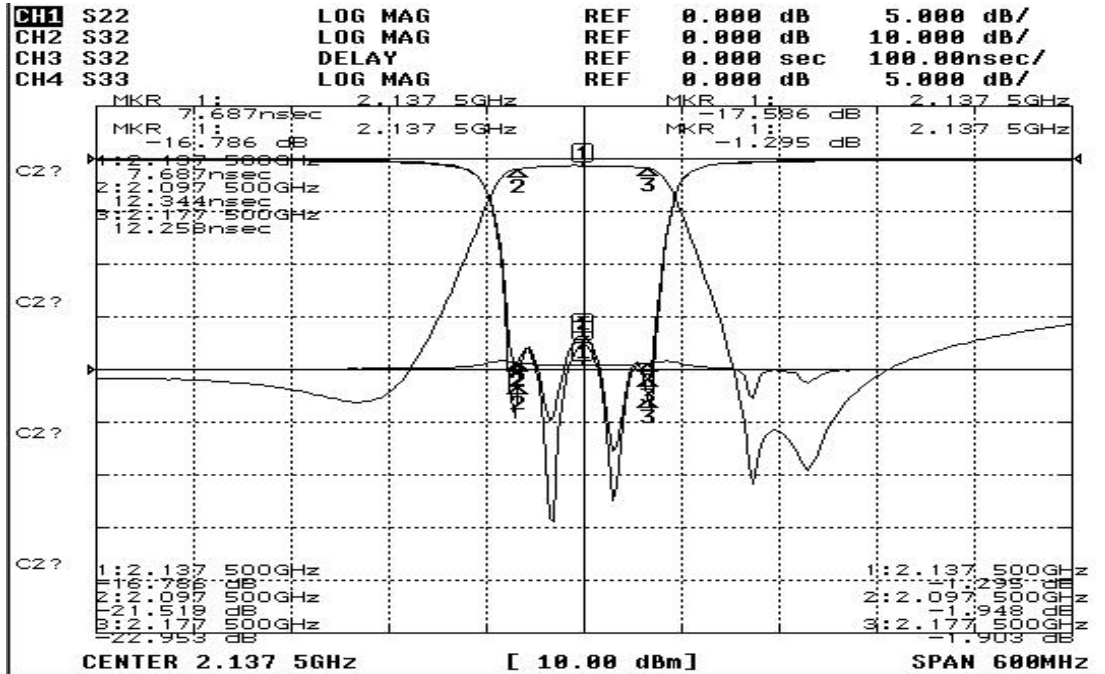
ITEMS	SPEC	UNIT
Center Frequency [fo]	2137	MHz
Bandwidth [BW]	fo ±40 [2097 ~ 2177 ]	MHz
Insertion Loss in BW	2.7	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	38dB min @ fo ±100 [ 1980 ]	MHz
	28dB min @ fo ± [ 1980~ 2050]	MHz
	27dB min @ fo ± [ 2250~ 2400]	MHz
	dB min @ fo ± [ ~ ]	MHz
Group Delay Variation		ns max
Input Power	2	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

Mechanical Specification



 I/O PORT  
 GROUND  
 TOLERANCE : ±0.2  
 UNIT: mm

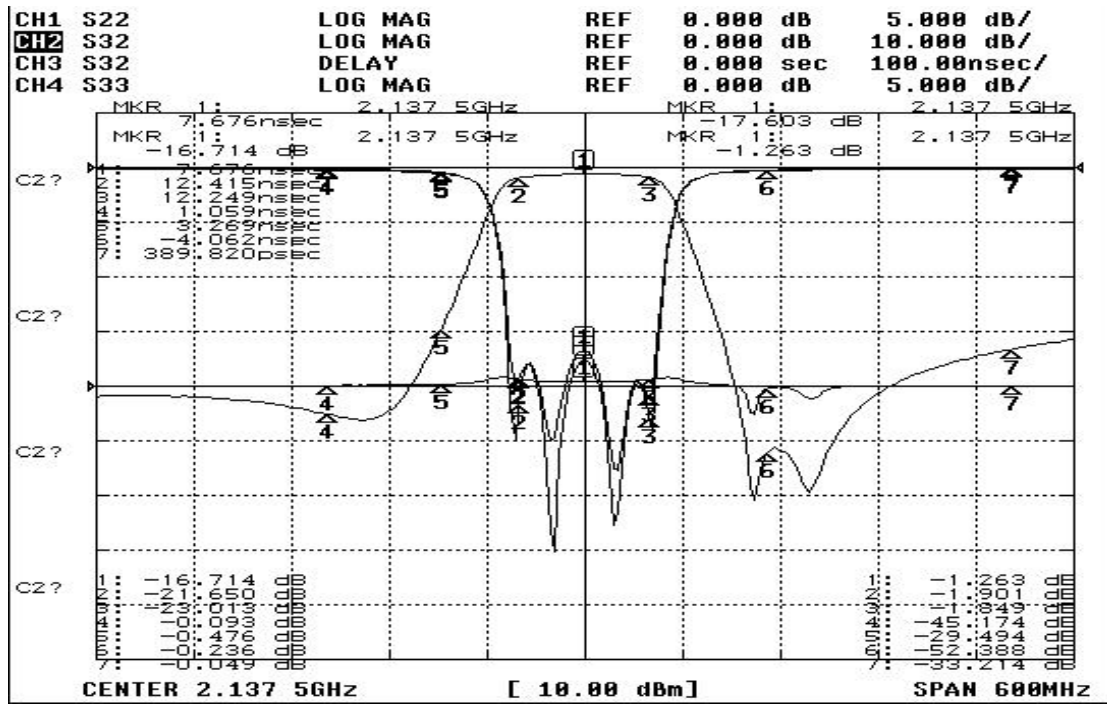
Plot Data



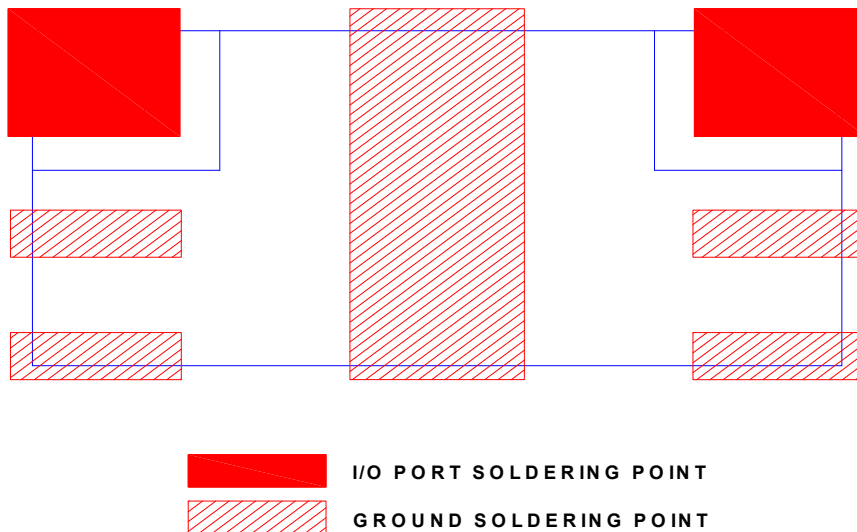
CH2 MARKER LIST			
1	2.137	5.000	0.000
2	2.097	5.000	-1.948
3	2.177	5.000	-1.903
4	2.000	5.000	-1.295
5	2.000	5.000	-1.295
6	2.000	5.000	-1.295
7	2.000	5.000	-1.295

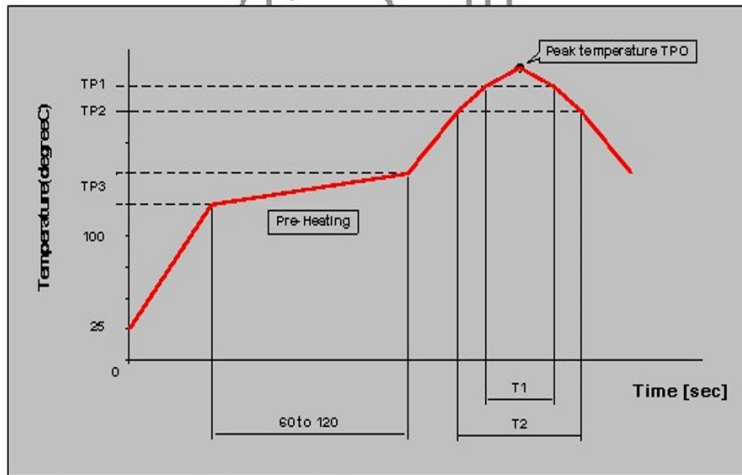
CH4 MARKER LIST			
1	2.137	5.000	-1.275
2	2.097	5.000	-1.948
3	2.177	5.000	-1.903
4	2.000	5.000	-1.295
5	2.000	5.000	-1.295
6	2.000	5.000	-1.295
7	2.000	5.000	-1.295



 Recommended PC Board Pattern



 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180